

Claim 1 (amended). A test configuration, comprising:

a semiconductor wafer;

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a plurality of semiconductor chips disposed on said semiconductor wafer, each of said plurality of semiconductor chips having a self-test unit generating test information for functionally checking said semiconductor chip; and

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an energy source for providing an electrical energy supply from energy fed in contactlessly, said energy source disposed on said semiconductor wafer and connected to said semiconductor chip for providing the electrical energy supply to said semiconductor chip, said energy source having at least one solar cell for generating an operating current for said semiconductor chip by optical radiation fed in contactlessly;

said semiconductor wafer having a scribe line for separating said plurality of semiconductor chips from one another, and said solar cell being disposed in said scribe line.

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Claim 6 (amended). The test configuration according to claim 1, wherein said solar cell is disposed on a surface of said semiconductor wafer which is remote from said semiconductor chip, said semiconductor wafer having an electrically conductive plated-through hole formed therein disposed between

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said solar cell and said semiconductor chip, at a boundary
between said plated-through hole and said semiconductor wafer,
said semiconductor wafer has a pn junction disposed along said
plated-through hole for preventing a current flow between said
plated-through hole and a remainder of said semiconductor
wafer.

Claim 7(amended). The test configuration according to claim
1, including a radiation-absorbing layer disposed between said
solar cell and said semiconductor chip.

Add the Following Claim:

20. A test configuration, comprising:

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a semiconductor wafer;

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a semiconductor chip disposed on said semiconductor wafer,
said semiconductor chip having a self-test unit generating
test information for functionally checking said semiconductor
chip; and

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an energy source for providing an electrical energy supply
from energy fed in contactlessly, said energy source disposed
on said semiconductor wafer and connected to said
semiconductor chip for providing the electrical energy supply
to said semiconductor chip, said energy source having at least

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one solar cell for generating an operating current for said
semiconductor chip by optical radiation fed in contactlessly,
said solar cell being disposed areally on a surface of said
semiconductor wafer.